This Sheet Has Been Replaced

ABSTRACT OF THE DISCLOSURE

In a ball grid array type semiconductor device mounted on a printed wiring board, the external terminals can be prevented from being broken down even when the ambient temperature on the device is repeatedly changed. A flexible adhesive member for gluing the semiconductor chip to an insulating tape is provided to cover up to a region including the lands to which the external terminals are bonded and which are provided on the insulating tape surface. The flexible adhesive member for covering the lands may be replaced by a flexible low-elasticity member.